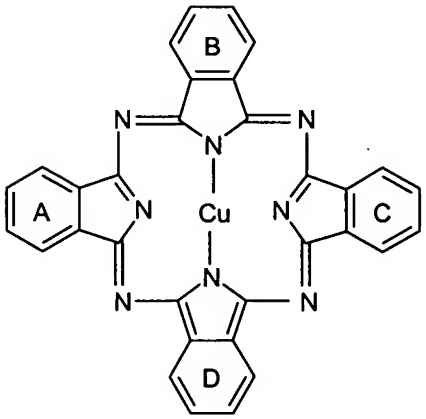
In the claims

1. (currently amemded): A photosensitive resin composition comprising as a component (A) a green colorant of the formula



(1)

in which the rings A, B, C and D are substituted by hydroxy or by the moiety $-O-(CR_1R_2)_n-E$,

wherein R_1 is hydrogen or C_1-C_4-Alkyl, R_2 is hydrogen or C_1-C_4-Alkyl,

n is 0, 1, 2 or 3 and the ring E is unsubstituted or substituted by C_1-C_6alkyl, C_1-C_6alkoxy, hydroxy, $NHCOR_3$, $NHSO_2R_4$ or SO_2NHR_5, wherein R_3 is C_1-C_4-Alkyl or phenyl, R_4 is C_1-C_4-Alkyl or phenyl and R_5 is is C_1-C_4-Alkyl or phenyl,

b) as a component (B) an alkali soluble reactive or unreactive oligomer or reactive or unreactive polymer ~~(reactive or unreactive)~~ ,

c) as a component (C) a polymerizable monomer,

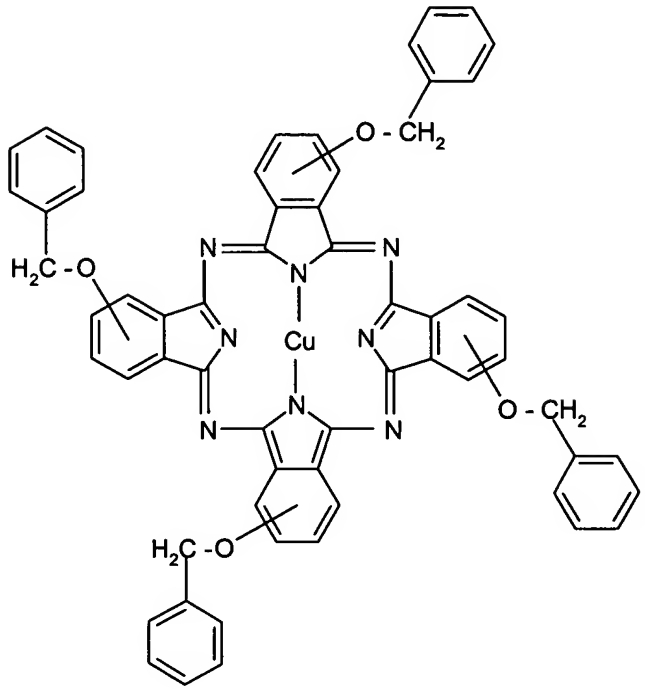
d) as a component (D) a photoinitiator,

e) as a component (E) an epoxy compound,

and also, if desired,

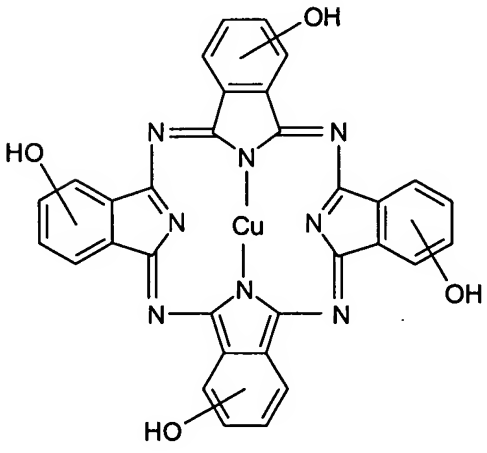
f) as a component (F) further additives.

2. (original): A photosensitive resin composition according to claim 1, wherein the component (A) is the colorant of formula



(2).

3. (original): A photosensitive resin composition according to claim 1, wherein the component (A) is the colorant of formula



(3).

4. **(currently amemded):** Solder resist process, ~~using the photosensitive resin composition according to any one of claims 1 to 3,~~ which process comprises the steps of

(1) mixing the components (A) to (E) and if desired (F) according to claim 1,

(2) applying the resulting composition to the substrate ~~("coating of the substrate")~~ to generate a coated substrate,

(3) evaporating ~~of~~ the solvent, if present, at a temperature between 80-90°C,

(4) exposing the coated substrate to irradiation through a negative mask or by a direct laser imaging,

(5) developing the irradiated sample by washing with aqueous alkaline solution and thereby removing the uncured areas,

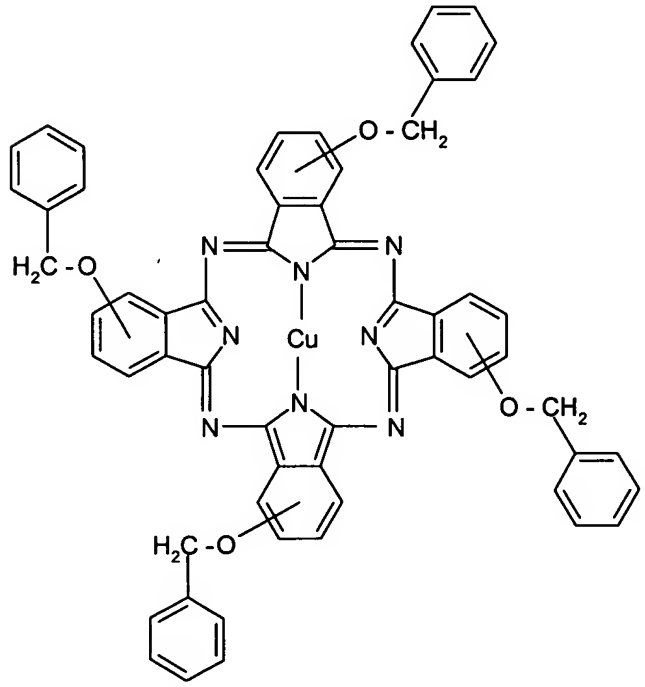
and

(6) thermally curing the sample at a temperature about 150°C, thereby initiating the crosslinking between the carboxylic acid and the epoxy component.

5. (original): Coated substrate obtained by the process according to claim 4.

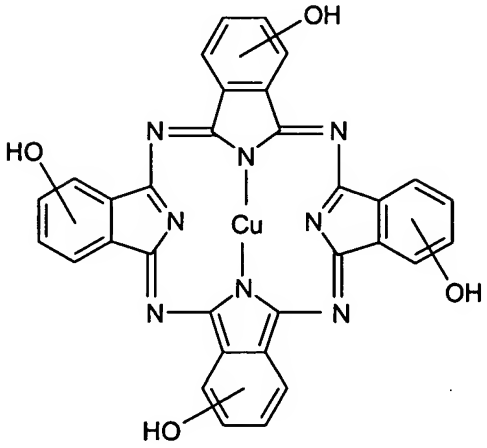
6. (currently amemded): Substrate coated with the photosensitive resin composition according to ~~any of~~ claim [[s]] 1~~, to 3.~~

7. (new): Solder resist process according to claim 4, wherein component (A) of step (1) is the colorant of formula



(2).

8. (new): Solder resist process according to claim 4, wherein component (A) of step (1)) is the colorant of formula



(3).

9. (new): Coated substrate obtained by the process according to claim 7.

10. (new): Coated substrate obtained by the process according to claim 8.

11. (new): Substrate coated with the photosensitive resin composition according to claim 2.

12. (new): Substrate coated with the photosensitive resin composition according to claim 3.